Contact Name Title - Contact Product Env-Stewards Product Enviro Compliance NA Product Env-Stewards Product Env-Stewards Product Env-Stewards Product Enviro Compliance NA Product Env-Stewards Product Env-Stewards	ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
Company name	752-21.1										als and Mfg	Informati	on		
Semilar Contact Name Title - Contact Phone - Contact Phone - Contact Email - Contact Emailar - Contact Product Enviro Compliance NA Product Env-Stewards@onsemi.com Interview Product Enviro Compliance NA Product Env-Stewards@onsemi.com Product Enviro Compliance NA Product Env-Stewards@onsemi.com Product Enviro Compliance NA Product Env-Stewards@onsemi.com Product Env-Stewards Product Enviro Compliance NA Product Env-Stewards@onsemi.com Product Env-Stewards@onsemi	upplier Informa	ation								,					
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Product Env-Stewards Authorized Representative* Title - Representative Product Enviro Compliance Product Enviro Compliance NA Product Enviro Compliance NA Product Env-Stewards Product Enviro Compliance NA Product Env-Stewards Product Enviro Compliance NA Product Env-Stewards © onsemi.com NA Product-Env-Stewards © onsemi.com NA Na Version Na Vers	nsemi											2024-05-01			
Authorized Representative* Product-Env-Stewards Product Enviro Compliance Product Env-Stewards Product Env-Stewards Product Env-Stewards Product-Env-Stewards Prod	Contact Name			Title - Contact			1	Phone - Contact*				Email - Contact*			
Product Envis Compliance Requester Item Number Mfr Item Number Manufacturing Site Weight* UOM Unit of CNJ Number Of Reflow Cycles Matter Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds Manufacturing Site Weight* UOM Unit of CNJ Number of Reflow Cycles Mfr Item Number Manufacturing Site Manufacturing Site Weight* Number of Reflow Cycles Matter Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds Manufacturing Site Manufacturing Si	Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	Authorized Representative*			Title - Representative			I	Phone - Representative*				Email - Representative*			
FDMS86310 FET 80V 4.8 mOhm PQFN56 2024-05-01 CNJ 104.003 mg Each Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 Matte Tin (Sn) - annealed Seconds Seconds Seconds	Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds Somments Evel 1 - maximum time at peak temperature during soldering is 10-30 seconds	Requester	r Item Number	Mfr Item	m Number Mfr Item Name				Effective Date	Version	N	Manufacturing Site	W	eight*	UOM	Unit Type
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles 260 Comments Evel 1 - maximum time at peak temperature during soldering is 10-30 seconds			FDMS86	310	FET 80V 4.8 mOhn	n PQFN56		2024-05-01		C	CNJ		4.003	mg	Each
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 omments vel 1 - maximum time at peak temperature during soldering is 10-30 seconds				arminal Reso	Alloy	STD 020 MSI	Pating	Dank Prog	ease Rody T	amparatur	a May Time at Pools	Tamparatus	a Numb	or of Potlow Cya	lac
comments evel 1 - maximum time at peak temperature during soldering is 10-30 seconds	2			•		31D-020 M31	_ Kaung			T *				el of Kellow Cyc	ies
evel 1 - maximum time at peak temperature during soldering is 10-30 seconds	•	(Sii) - aimealeu	C	U Alloy	1			200		IC	30	seconds) 3		
1 1 0 0		mo at neak temperatura	during cal	doring is 10.3	10 seconds										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting tempe	erature type solders (i.e. lead based solder	alloys containing 85% by weight or more lead).									
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	5.09	mg	Supplier	Silicon (Si)	7440-21-3		5.09	mg
Die Attach Solder	3.92	mg	Supplier	Silver (Ag)	7440-22-4		0.098	mg
			A	Lead (Pb)	7439-92-1	7a	3.626	mg
			Supplier	Tin (Sn)	7440-31-5		0.196	mg
Lead Frame	44.88		Supplier	Silver (Ag)	7440-22-4		0.1346	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0539	mg
			Supplier	Iron (Fe)	7439-89-6		1.0547	mg
			Supplier	Copper (Cu)	7440-50-8		43.6234	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0135	mg
Mold Compound-Black	47.25	mg		Proprietary	proprietary data		3.78	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2362	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		43.2337	mg
Plating	0.445	mg	Supplier	Tin (Sn)	7440-31-5		0.445	mg
Wire Bond - Al	2.364	mg	Supplier	Aluminum (Al)	7429-90-5		2.364	mg
Wire Bond - Cu	0.054	mg	Supplier	Copper (Cu)	7440-50-8		0.054	mg